PRODUCTS AFFECTED:

- SP3070EEN-L
- SP3071EEN-L
- SP3072EEN-L
- SP3073EEN-L
- SP3074EEN-L
- SP3075EEN-L
- SP3076EEN-L
- SP3077EEN-L
- SP3078EEN-L

- SP3070EEN-L/TR
- SP3071EEN-L/TR
- SP3072EEN-L/TR
- SP3073EEN-L/TR
- SP3074EEN-L/TR
- SP3075EEN-L/TR
- SP3076EEN-L/TR
- SP3077EEN-L/TR
- SP3078EEN-L/TR

CHANGE CATEGORY:

- ☑ Process
- ☐ Material
- ☐ Design
- ☐ Package
- ☐ Datasheet
- ☐ Packing/Shipping
- ☑ Other: Alternate Foundry and Assembly/Test Site

DESCRIPTION OF CHANGE:

- Qualification of 0.25um CMOS process at TSMC.
- Qualification of alternate assembly sites, Carsem (for 8 and 14L nSOIC) and ASE Chung-Li (for 8L nSOIC).

IMPACT OF CHANGE:

There is no change to product form, fit or function.

TARGET IMPLEMENTATION DATE: 09-DECEMBER-2013

Please contact customer support (customersupport@exar.com) for sample date availability or qualification data.